



THE BREADBOARDING MEDIUM FOR SURFACE MOUNT TM

33000 SERIES APPLICATION SPECIFIC ADAPTERS IDS33113 REV 1-2012

FOR TO-263AB 33113 MODEL 3-LEAD D PACKAGE ALWAYS CONSULT DEVICE DATA SHEET TO INSURE PROPER FIT - B -GND PAD .420 in. (10.66 mm) Wide .375 in. (9.52 mm) High PINS ON .1 in. CENTERS PROVIDE ന COMPATIBILITY WITH I **BREADBOARDS AND** SOCKETS, TWO PINS m I ARE PROVIDED FOR ന ന EACH DEVICE LEAD D FOR GREATER A CURRENT CAPACITY. н NOTE: CIRCUIT FOILS AND OUTPUT PINS MAY NOT BE SUITABLE FOR OPERATION AT I-----I HIGHEST RATED DEVICE G Е CURRENT LEVELS. EXTREME TEMPERATURE RISE MAY RESULT IN FAILURE. SINGLE-IN-LINE (SIP) PINS ON .1 in. CENTERS. TWO PER DEVICE LEAD. SEE PIN **PIN SPECIFICATIONS / TOLERANCES** SPECS. С In Inches A = 0.62 + 0.06F B = .130 +- .010 C =.100 +- .005 Â D = .020 +- .004

B .600 15.24 BOARD WIDTH +5mm .020in.	FIG.	INCHES	ММ	NOTE:
C .100 2.54 SIP PIN SPACE +20mm.008in. D .625 15.87 PAD (DEVICE) MAX E .100 2.54 DEVICE LEAD PITCH F .100 2.54 PAD LENGTH	Α	.800	20.32	BOARD HEIGHT +5mm .020in.
D .625 15.87 PAD (DEVICE) MAX E .100 2.54 DEVICE LEAD PITCH F .100 2.54 PAD LENGTH	в	.600	15.24	BOARD WIDTH +5mm .020in.
E .100 2.54 DEVICE LEAD PITCH F .100 2.54 PAD LENGTH	С	.100	2.54	SIP PIN SPACE +20mm .008in.
F .100 2.54 PAD LENGTH	D	.625	15.87	PAD (DEVICE) MAX
	Е	.100	2.54	DEVICE LEAD PITCH
G .070 1.77 PAD WIDTH	F	.100	2.54	PAD LENGTH
	G	.070	1.77	PAD WIDTH
H .150 3.81 GAP	н	.150	3.81	GAP

BOARD MATER Thick G-10 FR-4 CIRCUITS: 1 oz

B

BOARD MATERIAL: .8mm, +-.13mm .031in+-..005 in. Thick G-10 FR-4 Glass Epoxy or equivalent. CIRCUITS: 1 oz. Copper with RoHS compliant Lead Free solder coating. Patten Position on board +-

SPECIFICATIONS

D

E = .031 +-.005

.5mm .020in. TOLERANCES: If not noted are +- 20%. Nominal values are given. Controlling unit is Millimeters. Values rounded to nearest decimal. Slight Variations due to manufacturing process can occur.

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